

2. Features

- *Stable and reliable in performances
- *Low temperature coefficient of frequency
- *Low profile, compact size
- *RoHS compliance
- *SMT processes compatible

3. Applications

*Bluetooth earphone systems

- *Hand-held devices when WiFi /Bluetooth functions are needed, e.g., Smart phone. *IEEE802.11 b/g/n
- *ZigBee

*Wireless PCMCIA cards or USB dongle

4. Description

Ying feng chip antenna series are specially designed for WiFi/Bluetooth applications. Based on yingfeng proprietary design and processes, this chip antenna has excellent stability and sensitivity to consistently provide high signal reception efficiency.

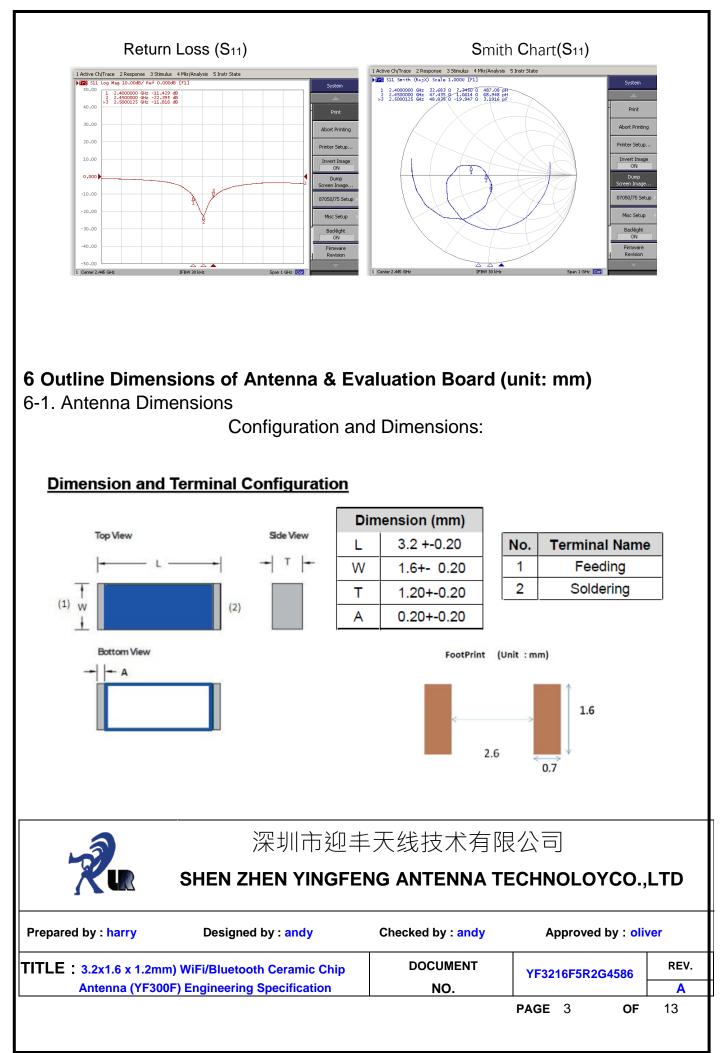
5. Electrical Specifications (40 x 40 mm² ground plane)

5-1. Electrical Table

	Characteristics	Specifications	Unit
Outline D	limensions	3.2x1.6x1.2	mm
Working	Frequency	2400~2500	MHz
VSWR		2 Max.	
Impedan	ce	50	Ω
Polarizat	ion	Linear Polarization	
Coin	Peak	5.29 (typical)	
Gain	Efficiency	75 (typical)	%

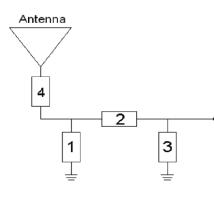
5-2. Return Loss & VSWR



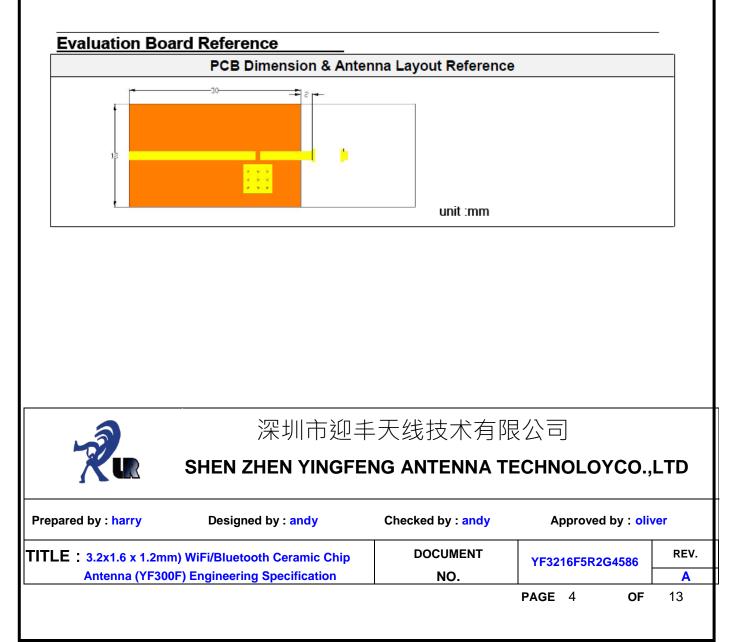


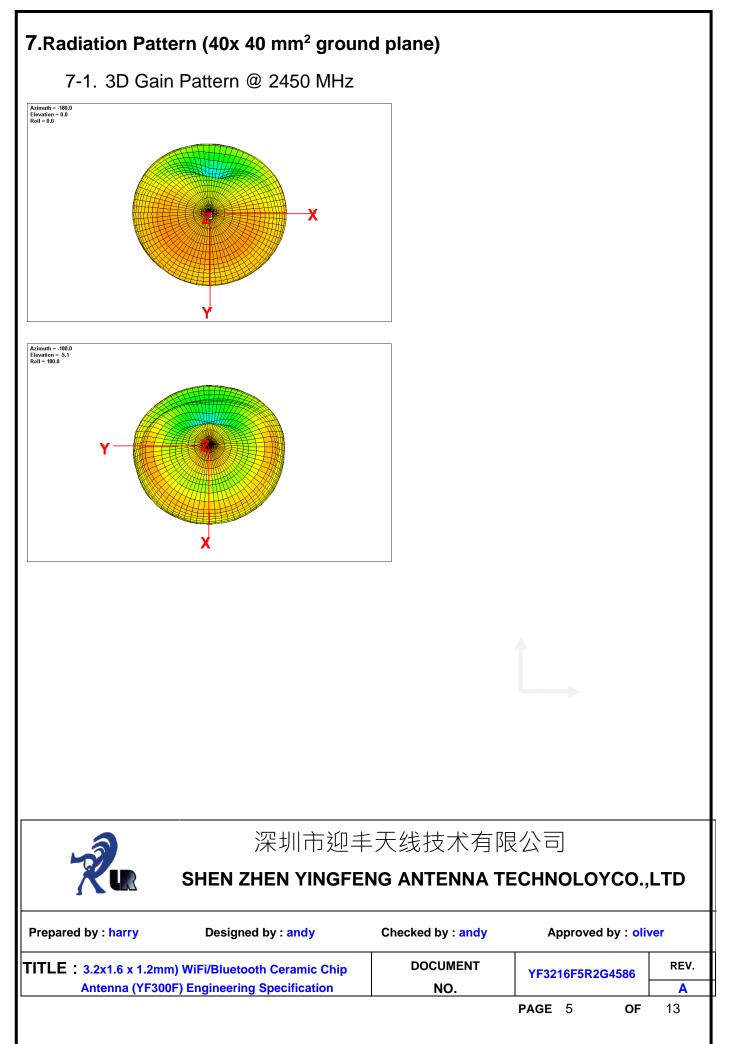
6-2-2. Matching Circuit:

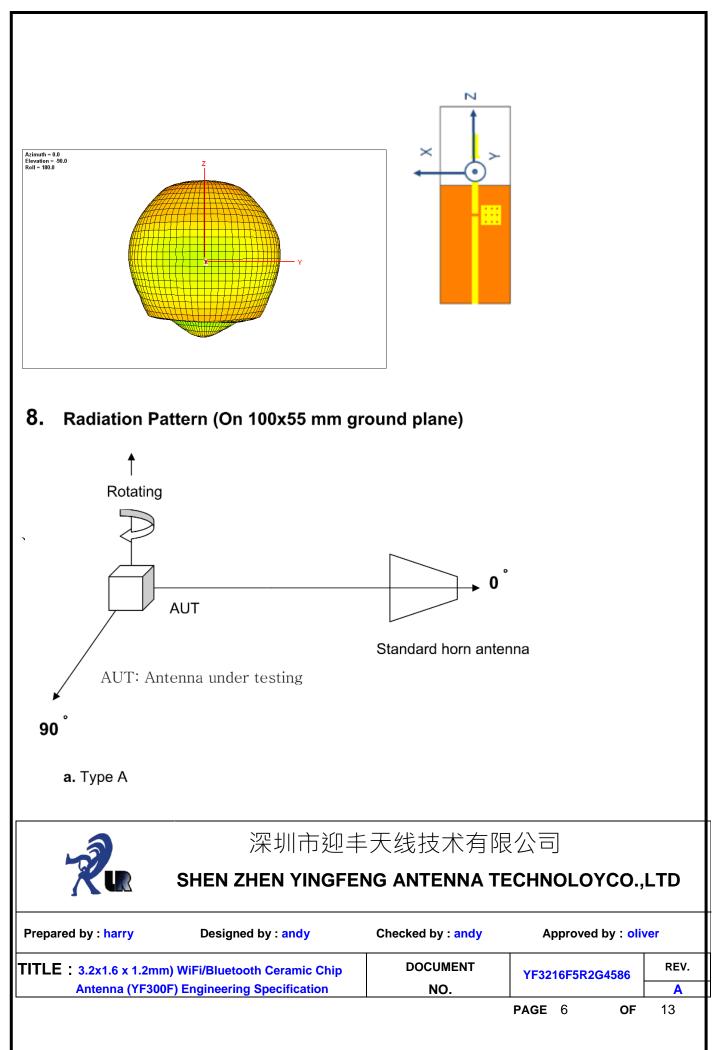
With the following recommended values of matching and tuning components, the center frequencies will be about 2450 MHz at our standard 40x40 mm² evaluation board. However, these are reference values, may need to be changed when the circuit boards or part vendors are different.

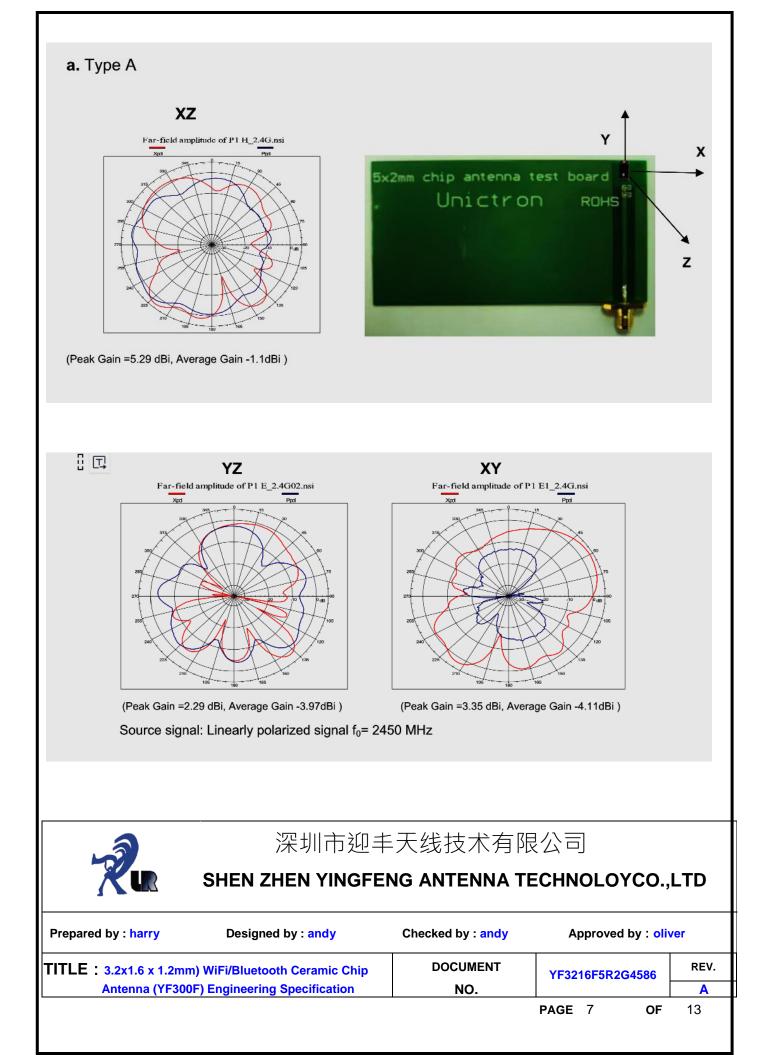


System Matching Circuit Component			
Location	Description	Vendor	
1	N/A*	-	
2	3.3nH, (0402)	DARFON	
3	1.5pF, (0402)	MURATA	
4	0 Ω, (0402)	-	

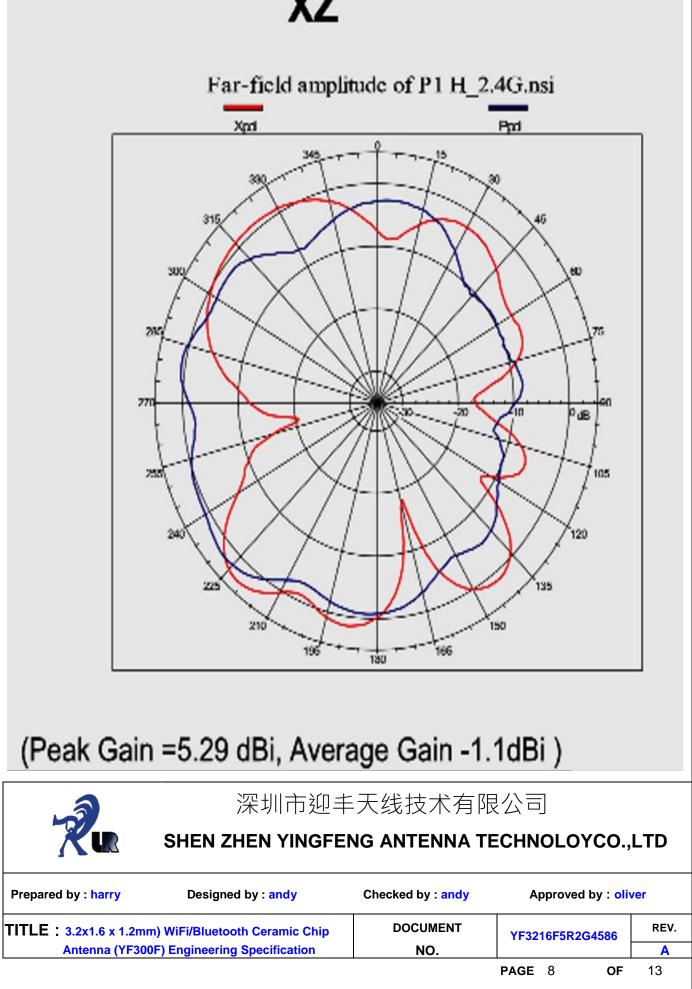


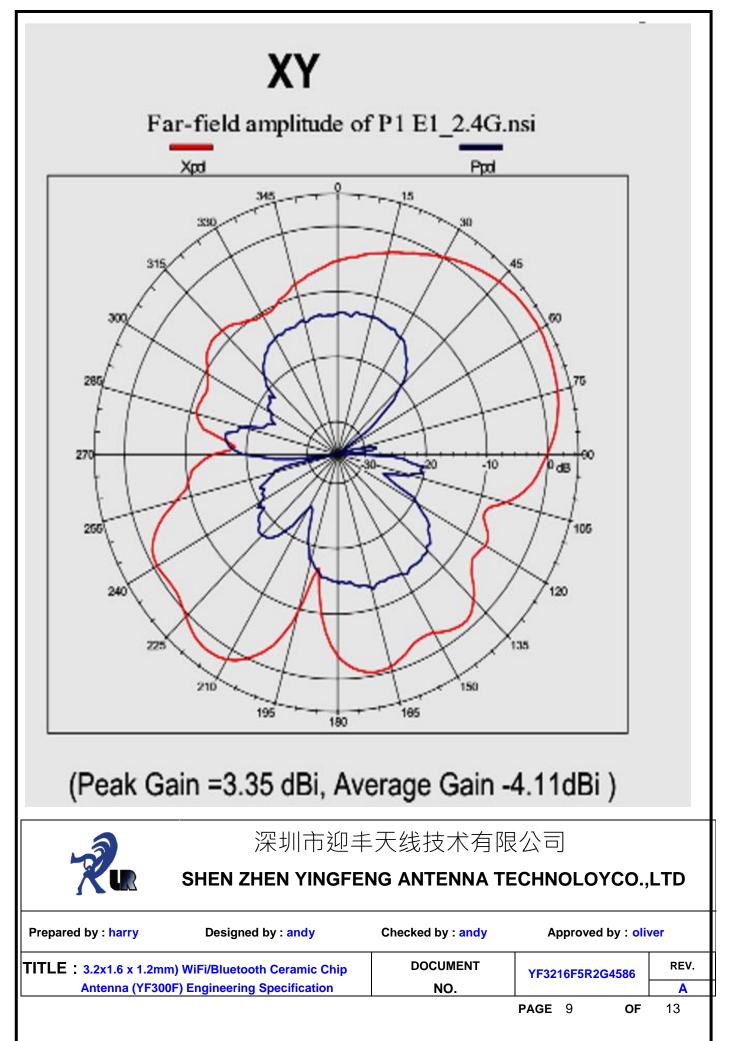


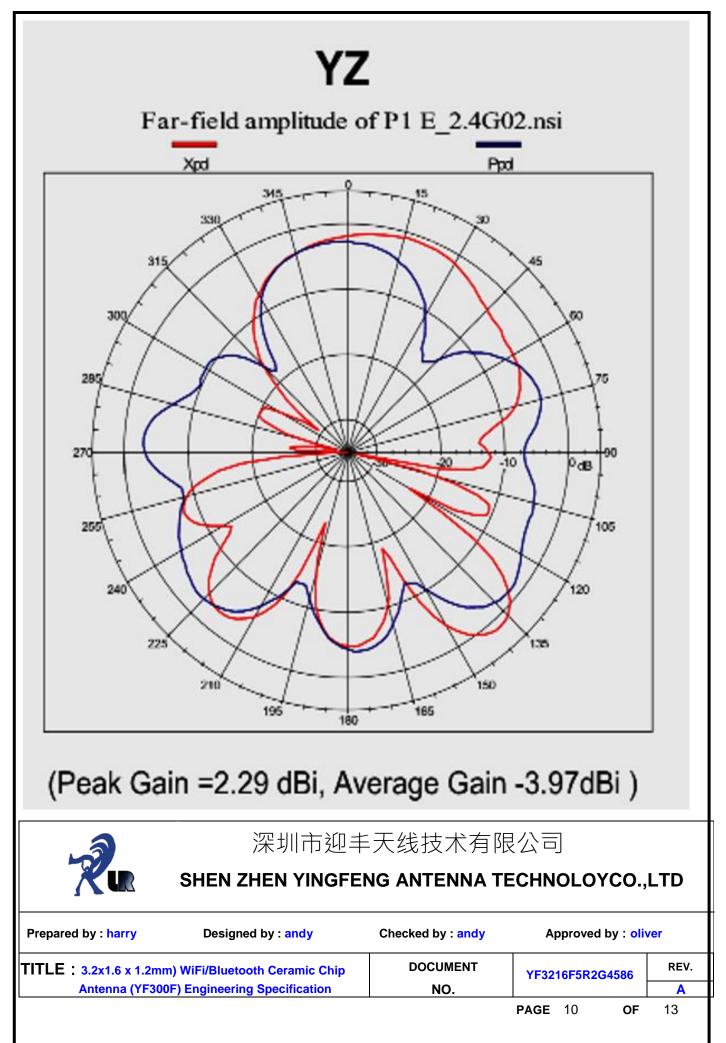




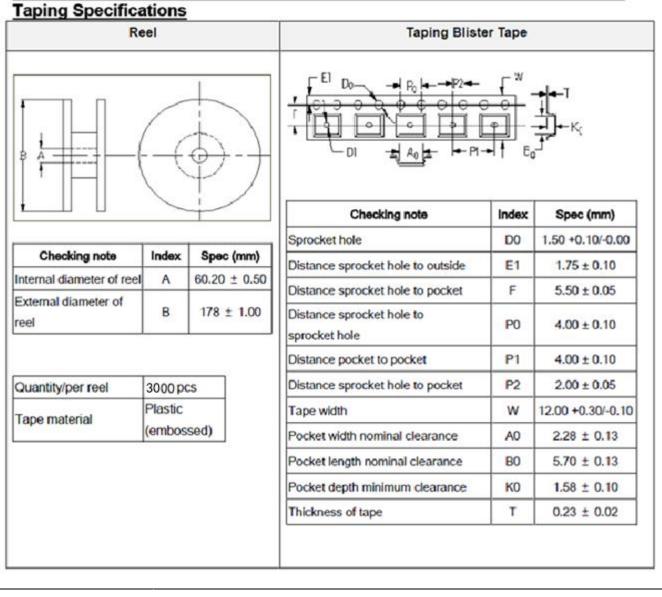








Complete machine free field OTA data				
SAND	TRP(dbm)	TIS(dbm)		
0	5.23	-91.07		
39	5.94	-91.33		
78	6.36	-91.32		





深圳市迎丰天线技术有限公司

SHEN ZHEN YINGFENG ANTENNA TECHNOLOYCO., LTD

Prepared by : harry	Designed by : andy	Checked by : andy	Approved	l by : <mark>oli</mark> v	/er
TITLE: 3.2x1.6 x 1.2mm	n) WiFi/Bluetooth Ceramic Chip	DOCUMENT	YF3216F5R2G4586		REV.
Antenna (YF300	F) Engineering Specification	NO.			Α
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Reliability Table

Test Item	Test Item Procedure Require Ceramic		Remark (Reference)	
Electrical Characterization		Fulfill the electrical specification	User Spec.	
Thermal Shock	 Preconditioning: 50 ± 10°C / 1 hr , then keep for 24 ± 1 hrs at room temp. Initial measure: Spec: refer Initial spec. Rapid change of temperature test: -30°C to +85°C; 100 cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature. 	No Visible Damage. Fulfill the electrical specification.	ML-STD-202 107	
Temperature Cycling	1. Initial measure: Spec: refer Initial spec. 2. 100 Cycles (-30℃ to +85℃), Soak Mode=1 (2 Cycle/hours). 3. Measurement at 24 ± 2Hours after test condition.	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104	
High Temperature Exposure	 Initial measure: Spec: refer Initial spec. Unpowered; 500hours @ T=+85℃. Measurement at 24 ± 2 hours after test. 	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108	
Low Temperature Storage	 Initial measure: Spec: refer Initial spec. Unpowered: 500hours @ T= -30 ℃. Measurement at 24 ± 2 hours after test. 	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108	
Solderability (SMD Bottom Side)	Dipping method: a. Temperature: 235 ± 5°C b. Dipping time: 3 ± 0.5s	The solder should cover over 95% of the critical area of bottom side.	IEC 60384-21/22 4.10	
Soldering Heat Resistance (RSH)	Preheating temperature: 150 ± 10°C. Preheating time: 1~2 min. Solder temperature: 260 ± 5°C. Dipping time: 5 ± 0.5s	No Visible Damage.	IEC 60384-21/22 4.10	
Vibration	5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz	No Visible Damage.	MIL-STD-202 Method 204	
Mechanical Shock	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine	No Visible Damage.	MIL-STD-202 Method 213	
Humidity Bias	1. Humidity: 85% R.H., Temperature: 85 ± 2 °C. 2. Time: 500 ± 24 hours. 3. Measurement at 24 ± 2hrs after test condition.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106	



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